

# MJE13005DRB

Rev.E May.-2016

## 描述 / Descriptions

TO-263 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a TO-263 Plastic Package.

## 特征 / Features

耐压高,开关速度快。

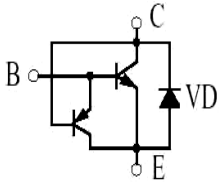
High voltage capability, high speed switching.

## 用途 / Applications

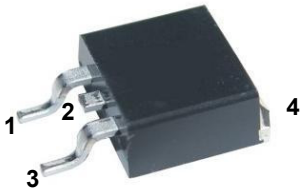
主要用于高频电子照明电路、开关及开关电源。

High frequency electronic lighting, switching power supply applications.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 : Base

PIN 2 : Collector

PIN 3 : Emitter

PIN 4 : VD

## 放大及印章代码 / $h_{FE}$ Classifications & Marking

见印章说明。 See Marking Instructions .

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

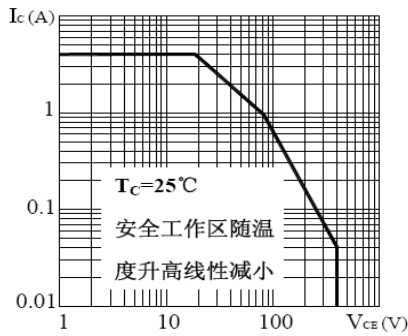
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	$V_{CBO}$	700	V
Collector to Emitter Voltage	$V_{CEO}$	400	V
Emitter to Base Voltage	$V_{EBO}$	9.0	V
Collector Current - Continuous	$I_C$	4.0	A
Collector Power Dissipation	$P_C$	2.0	W
Collector Power Dissipation	$P_C(T_C=25^\circ\text{C})$	75	W
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

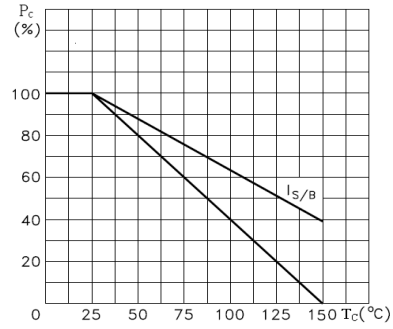
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=1\text{mA}$ $I_E=0$	700			V
Collector Cut-Off Current	$V_{CEO}$	$I_C=10\text{mA}$ $I_B=0$	400			V
Emitter Base Cut-Off Current	$V_{EBO}$	$I_E=1\text{mA}$ $I_C=0$	9.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=700\text{V}$ $I_E=0$			0.1	mA
Collector cut-off current	$I_{CEO}$	$V_{CE}=400\text{V}$ $I_B=0$			0.1	mA
Emitter Base Cut-Off Current	$I_{EBO}$	$V_{EB}=9.0\text{V}$ $I_C=0$			0.1	mA
DC Current Gain	$h_{FE}$	$V_{CE}=5.0\text{V}$ $I_C=1.0\text{A}$	10		40	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=2.0\text{A}$ $I_B=0.5\text{A}$			0.8	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=2.0\text{A}$ $I_B=0.5\text{A}$			1.2	V
Transition Frequency	$f_T$	$V_{CE}=10\text{V}$ $I_C=0.5\text{A}$ $f=1.0\text{MHz}$	7.0			MHz
Fall time	$t_f$	$V_{CE}=5\text{V}$ $I_C=0.5\text{A}$ (UI9600)			0.8	μs
Storage time	$t_s$				4.0	μs

电参数曲线图 / Electrical Characteristic Curve

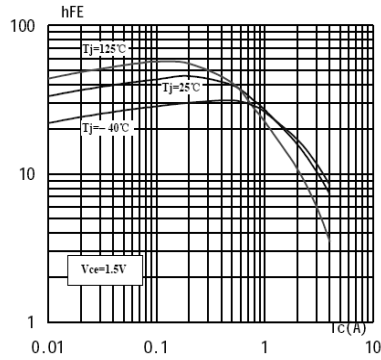
SOA(DC)



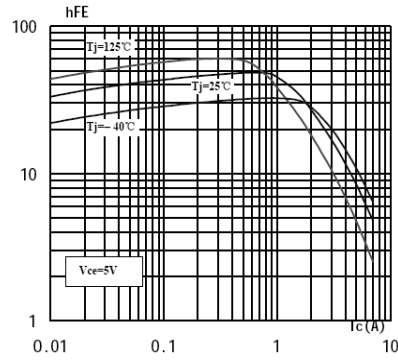
$P_c-T_c$



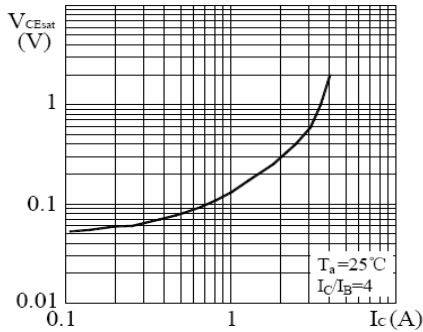
$h_{FE}-I_c$



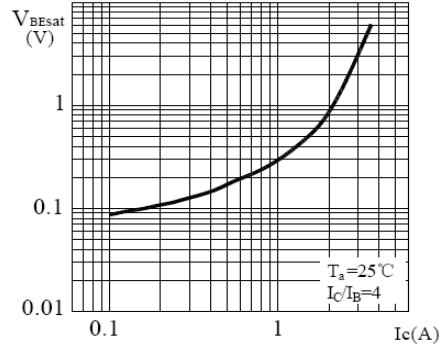
$h_{FE}-I_c$



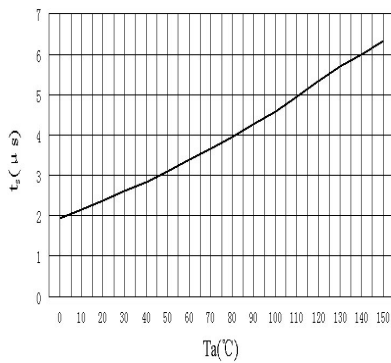
$V_{ces}-I_c$



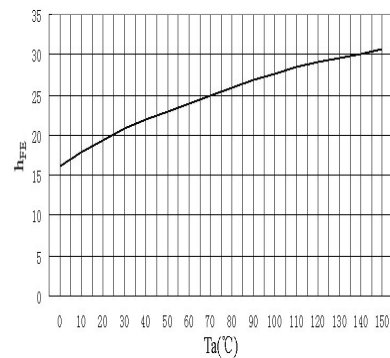
$V_{bes}-I_c$



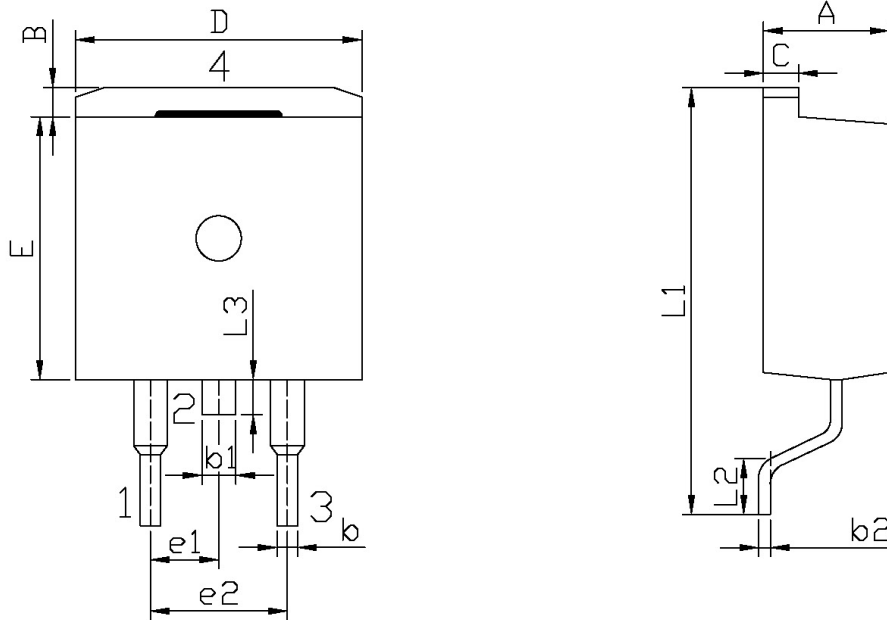
$t_s-T_a$



$h_{FE}-T_a$



外形尺寸图 / Package Dimensions

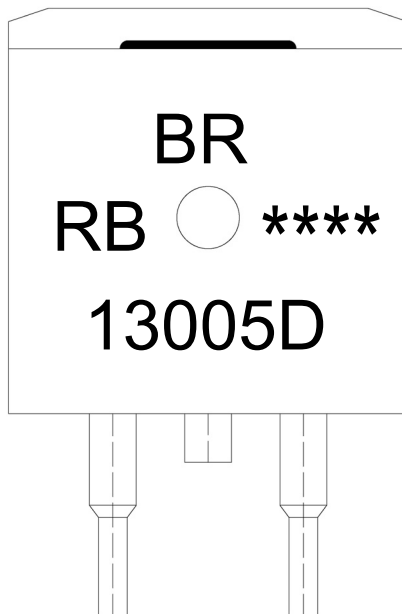


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74
b	0.70	0.90	e2	4.88	5.28
b1	1.15	1.35	L1	15.00	16.00
b2	0.40	0.60	L2	2.24	2.84
C	1.20	1.40	L3	1.20	1.60
D	9.80	10.20			

TO-263

## 印章说明 / Marking Instructions



说明：

BR： 为公司代码

13005D： 为型号代码

RB: 为规格代码

\*\*\*\*： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code

13005D: Product Type.

RB: Specification Code

\*\*\*\*: Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-263	800	1	800	5	4,000	13" x24	360×360×50	385×257×392

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-263	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180

**使用说明 / Notices**